		DARD			Π_	-			
	Operating Temperature Range		-55 °C to 105 °	°C (1)	Storage Temperature	e Range	-10 °C to 6	0 °C	(2)
Rating	Voltage Current		Signal Contact: 50 Power Contact: 200		Storage Hur	orage Humidity Range Relative humidity 8		% max	
			Signal Contact : 0.5 A		Operating H	lumidity Range	(Not dewed)		
			Power Contact : 3) NO				
		1		IFICATIO	JNS			1	
	EM		TEST METHOD			REQUI	REMENTS	QT	Α
CONSTRU		-						1	
General Examination		Visually and by measuring instrument.			Accord	ing to drawing.		×	×
Marking		Confirmed visually.						×	×
ELECTRIC CHARAC					lo: .	Cinnal Contact : 70m O. MAV			
Contact Resistance Insulation Resistance Voltage Proof		100 mA(DC or 1000Hz)			_	Signal Contact : $70m \Omega$ MAX. Power Contact : $20m \Omega$ MAX. Signal Contact : $100 M \Omega$ MIN. Power Contact : $1000 M \Omega$ MIN.			
		Signal Contact : 100 V DC.			_				-
		Power Contact : 250 V DC			Power				
		Signal Contact : 150 V AC for 1 min. Power Contact : 600 V AC for 1 min.			No flas	No flashover or breakdown.			×
MECHANIC								×	
INECHAINIC					Incertio	n Force	27 N MAX.	×	Ι_
Withdrawal Forces		Measured by applicable connector.				Insertion Force: 27 N MAX. Withdrawal Force: 3 N MIN.			
Mechanical Operation		100 times	100 times insertions and extractions.			ntact Resistanc		×	Ι-
					S	Signal Contact: 80m Ω MAX. Power Contact: 30m Ω MAX. ② No damage, crack and looseness of parts.			
Vibration		Frequency 10 to 55 to 10Hz, approx 5min				 No electrical discontinuity of 1 μs. 			<u> </u>
		Single amplitude : 0.75 mm, 10 cycles				No damage, crack and looseness of parts.			
		for 3 axial directions. 490 m/s ² , duration of pulse 11 ms						×	+_
Onook			for 3 both axial directions.						
ENVIRON	MENTAL C	HARACT	TERISTICS		•				
Damp Heat		Exposed a	at 40±2 °C, 90 ~ 95 %	, 96 h.	① Cor	ntact Resistanc	e:	×	_
(Steady state)					S	ignal Contact:	$80m\Omega$ MAX.		
Rapid Change of Temperature Cold Dry Heat		Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2~3 MIN) Exposed at -55°C, 96 h				Power Contact : 30m Ω MAX. ② Insulation Resistance: Signal Contact : 100 MΩ MIN. Power Contact : 1000 MΩ MIN. ③ No damage, crack and looseness of parts. ① Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. ② No damage, crack and looseness of parts.			-
					_				
									<u> </u>
			Exposed at 105°C, 96 h						
		Exposed a							<u> </u>
					2 No				
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68)			① No	No defect such as corrosion which impairs the function of connector. Contact Resistance:			-
					_				
					_				
						ignal Contact :			
Resistance to		1)Reflow	1)Reflow soldering :			Power Contact : 30m Ω MAX. No deformation of case of excessive			<u> </u>
	Soldering Heat		Peak TMP: 260°CMAX Reflow TMP: 220°CMIN for 60sec			looseness of the terminal.			
		0) 0-1-1	ng irons : 360°C MAX. for 5	sec.					
		2) Solderi	Soldered at solder temperature				g of solder shall cover a	×	_
Soldering Hea			at solder temperature			of OE 0/ of th	he surface being		
		Soldered	at solder temperature for immersion duration, 3 so	ec.			ne surface being		
Soldering Hea	T D	Soldered 240±3°C	•		immers SIGNED		CHECKED	DA	TE
Soldering Hea	T D	Soldered 240±3°C	for immersion duration, 3 so		immers			DA	TE
Soldering Heat Solderability COUNTAIN REMARKS	1) Include temper	Soldered 240±3°C	for immersion duration, 3 so ON OF REVISIONS	DES	immers			DA 18. 0	
Soldering Heat Solderability COUNTACT REMARKS	1) Include temper 2) "STORAGE" m	Soldered 240±3°C ESCRIPTIO ature rise causeans a long-te	for immersion duration, 3 so	DES	immers	sed.	CHECKED		5. 28
Soldering Heat Solderability COUNTACT REMARKS	1) Include temper	Soldered 240±3°C ESCRIPTIO ature rise causeans a long-te	for immersion duration, 3 so ON OF REVISIONS	DES	immers	APPROVED	CHECKED NH. NAKATA	18. 0 18. 0	5. 28 5. 28
Soldering Head Solderability COUNTANT REMARKS	1) Include temper 2) "STORAGE" m before assemb	Soldered 240±3°C ESCRIPTIO atture rise causeans a long-te ly to PCB.	ON OF REVISIONS sed by current-carrying. erm storage state for the unused pro	DES	immers	APPROVED CHECKED	CHECKED NH. NAKATA MK. NAGATA TS. 00N0	18. 0 18. 0	5. 2 5. 2 5. 2
Soldering Head Solderability COUNTAND REMARKS	1) Include temper 2) "STORAGE" m before assemb	Soldered 240±3°C ESCRIPTIO ature rise causeans a long-te ly to PCB.	for immersion duration, 3 so ON OF REVISIONS	DE:	immers	APPROVED CHECKED DESIGNED DRAWN	CHECKED NH. NAKATA MK. NAGATA	18. 0 18. 0 18. 0	5. 28 5. 28 5. 28
Soldering Head Solderability COUNTAND REMARKS	1) Include temper 2) "STORAGE" m before assemb erwise spec ualification Te	Soldered 240±3°C ESCRIPTIO ature rise causeans a long-te ly to PCB. iffied, referst AT:Ass	for immersion duration, 3 so ON OF REVISIONS sed by current-carrying. erm storage state for the unused pro to IEC 60512.	DE:	immers SIGNED	APPROVED CHECKED DESIGNED DRAWN G NO.	CHECKED NH. NAKATA MK. NAGATA TS. 00N0 TS. 00N0	18. 0 18. 0 18. 0 18. 0	5. 28 5. 28 5. 28